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(12) **United States Design Patent** (10) **Patent No.:** **US D999,747 S**
Tanikawa et al. (45) **Date of Patent:** **** Sep. 26, 2023**

(54) **SEMICONDUCTOR DEVICE**

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(73) Assignee: **ROHM CO., LTD.**, Kyoto (JP)
(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (14) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D13/182**
(58) **Field of Classification Search**
USPC D13/101, 110, 112, 118, 120, 123, 133,
D13/146, 147, 159, 154, 156, 174, 182,
D13/184, 199; D14/356, 433, 435, 438
CPC H01R 24/00; H01R 12/00; H01R 12/70;
H01R 13/62
See application file for complete search history.

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(57) **CLAIM**

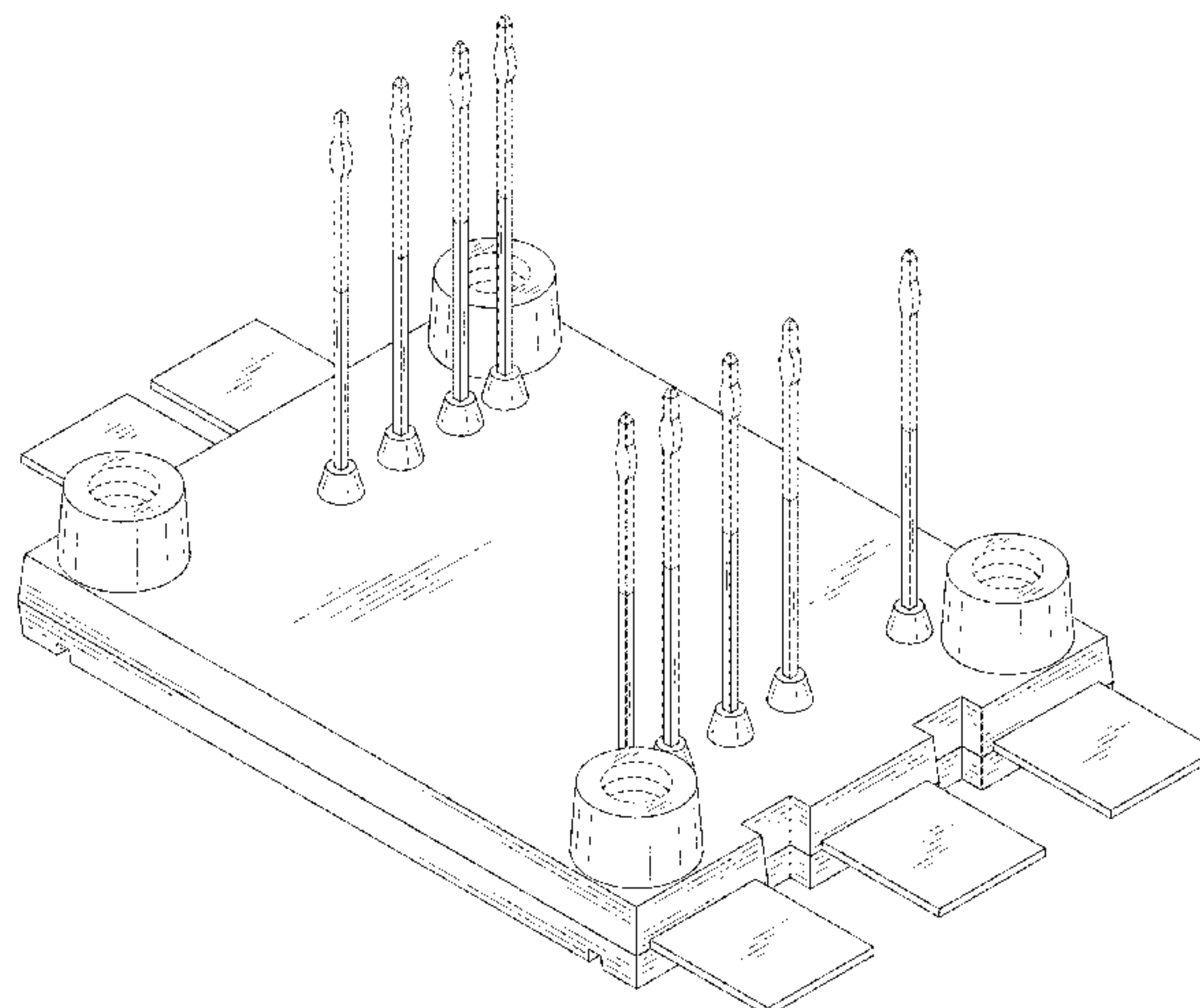
The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a front, top, and right side perspective view of a semiconductor device showing our new design;
FIG. 2 is a rear, bottom and left side perspective view thereof;
FIG. 3 is a front view thereof, the rear view being an identical image of FIG. 3;
FIG. 4 is a top plan view thereof;
FIG. 5 is a bottom plan view thereof;
FIG. 6 is a right side view thereof;
FIG. 7 is a left side view thereof;
FIG. 8 is an enlarged view of the portion indicated by line 8-8 in FIG. 6; and,
FIG. 9 is an enlarged view of the portion indicated by line 9-9 in FIG. 7.

The broken lines illustrate portions of the semiconductor device that form no part of the claimed design. The dash-dotted lines denote the boundary of the claim and form no part of the claimed design.

1 Claim, 9 Drawing Sheets



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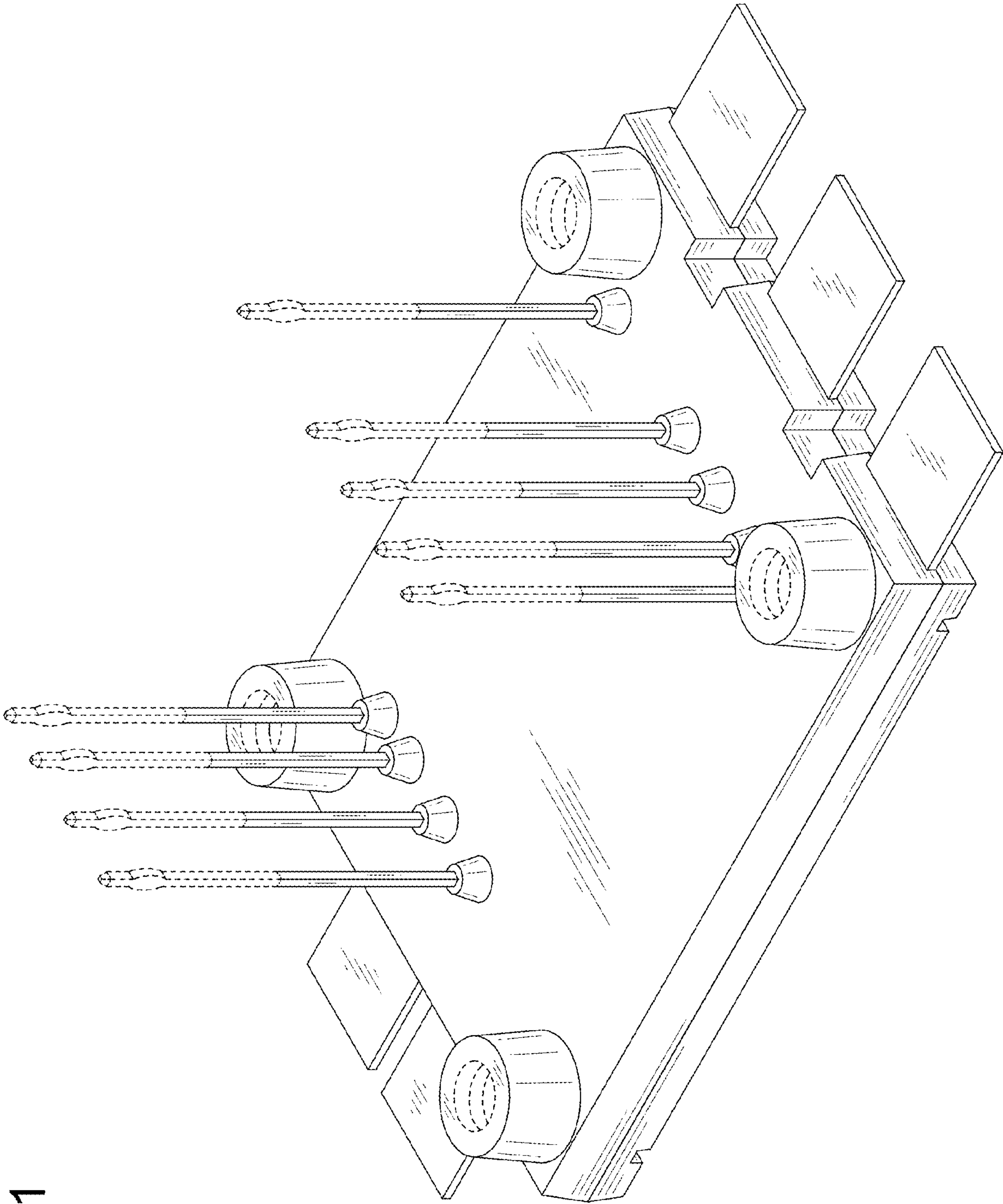


FIG.1

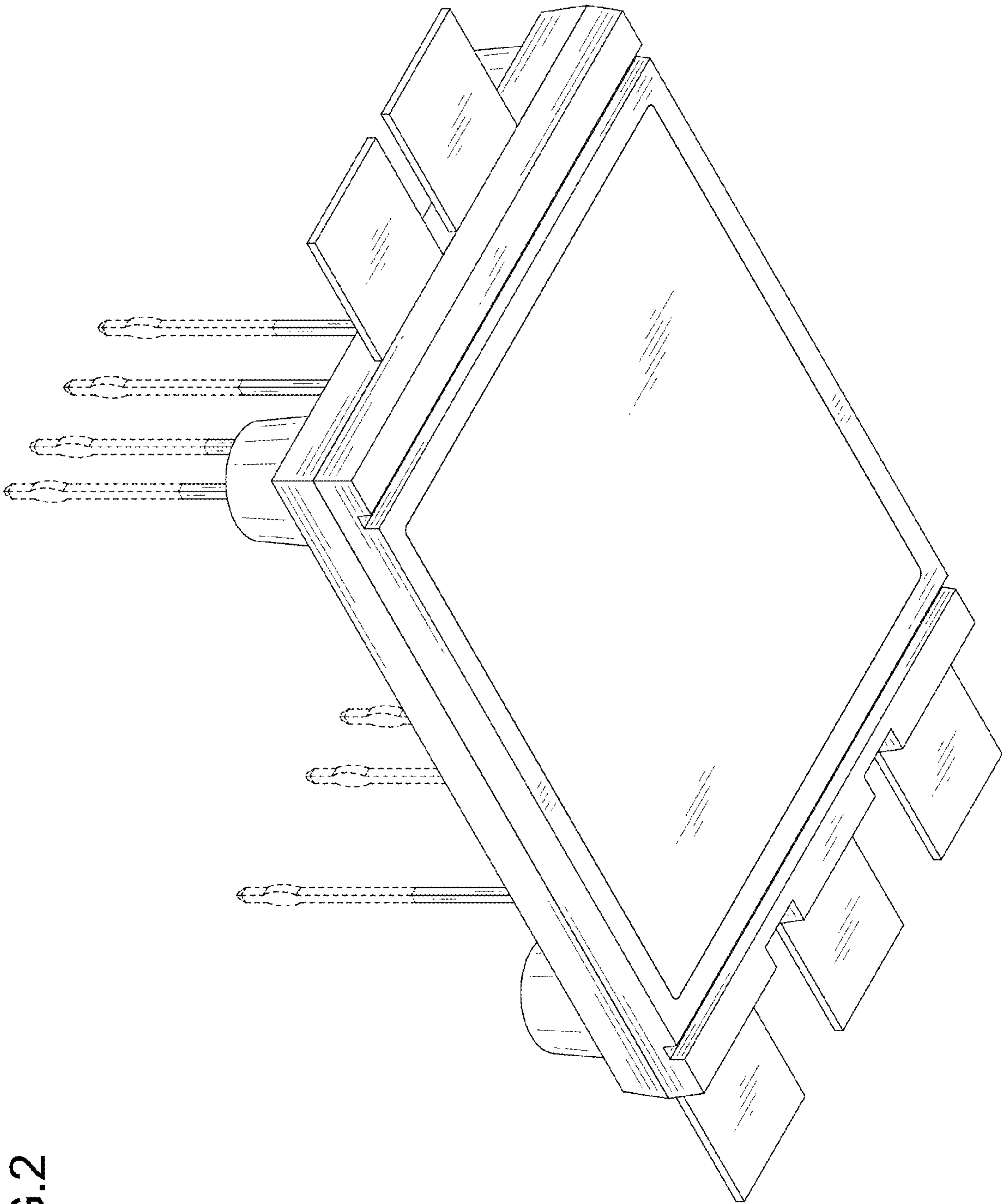
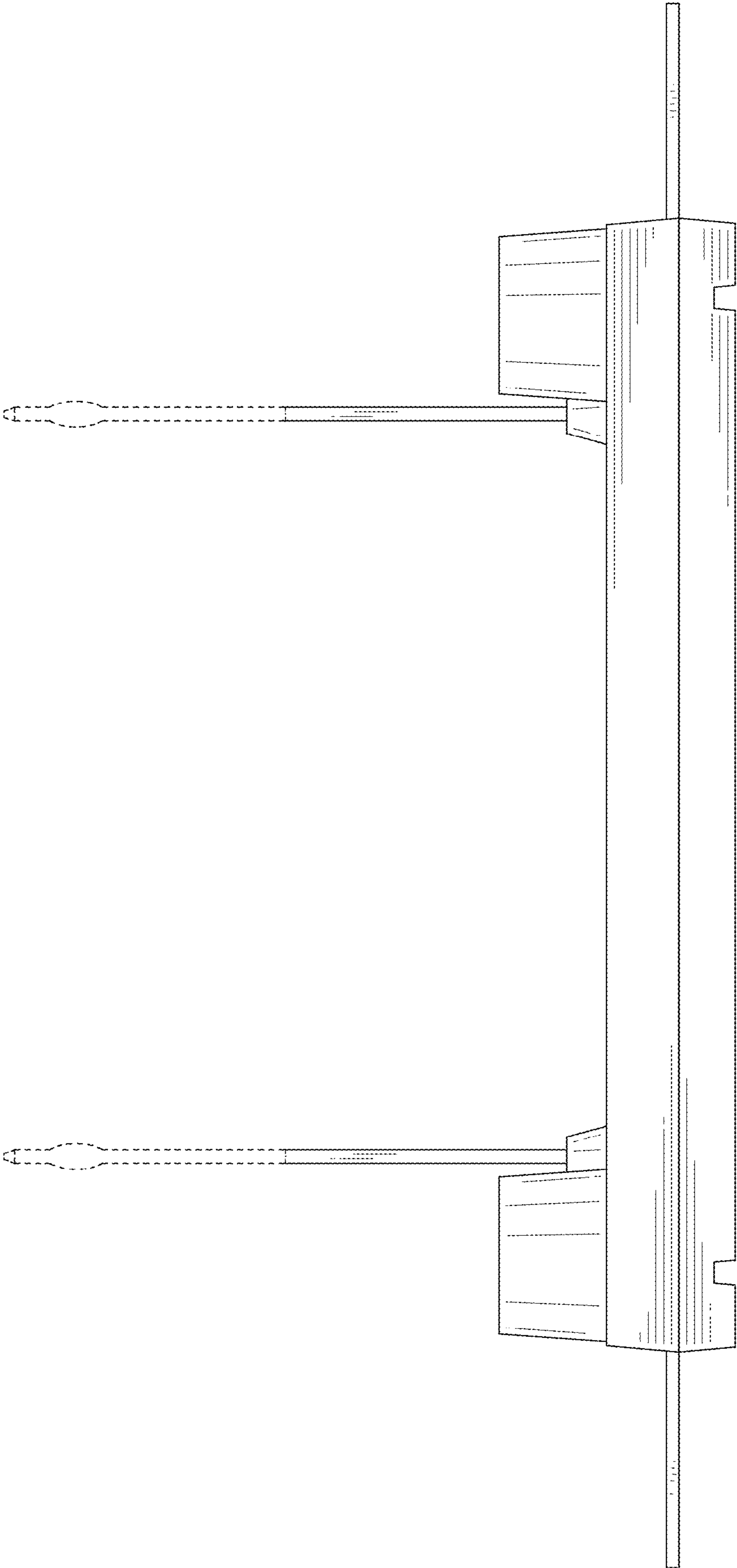


FIG.2

FIG.3



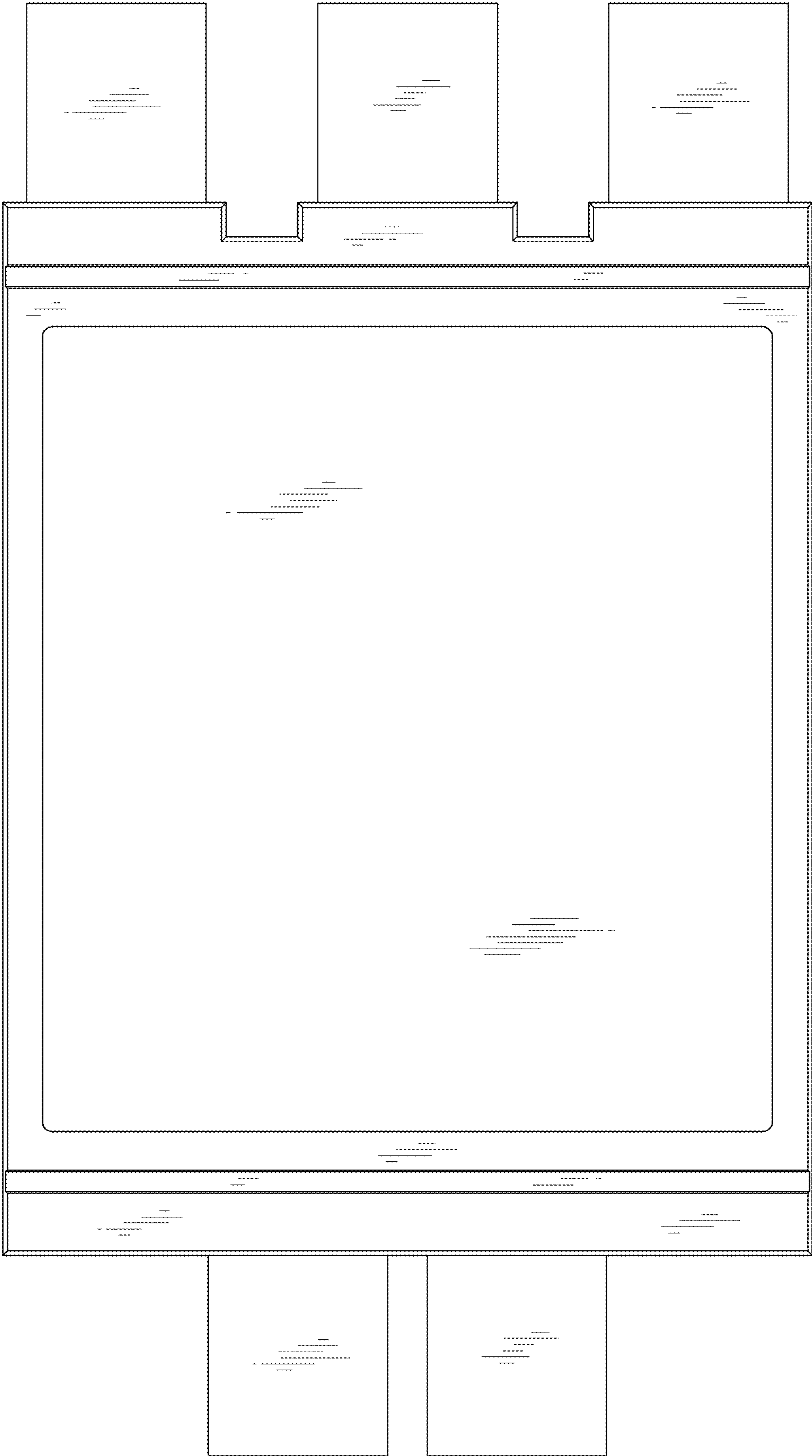


FIG.5

FIG.6

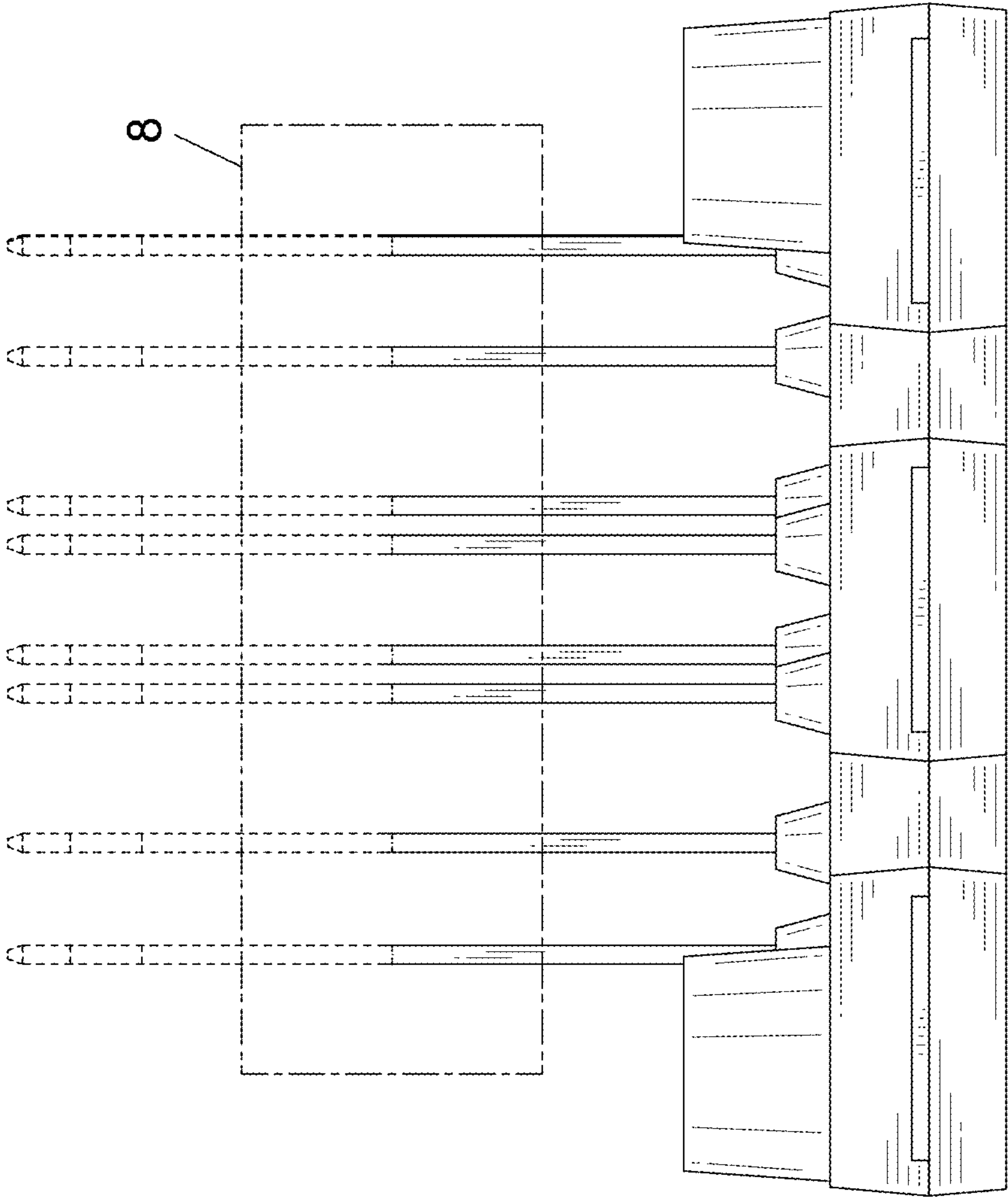


FIG.7

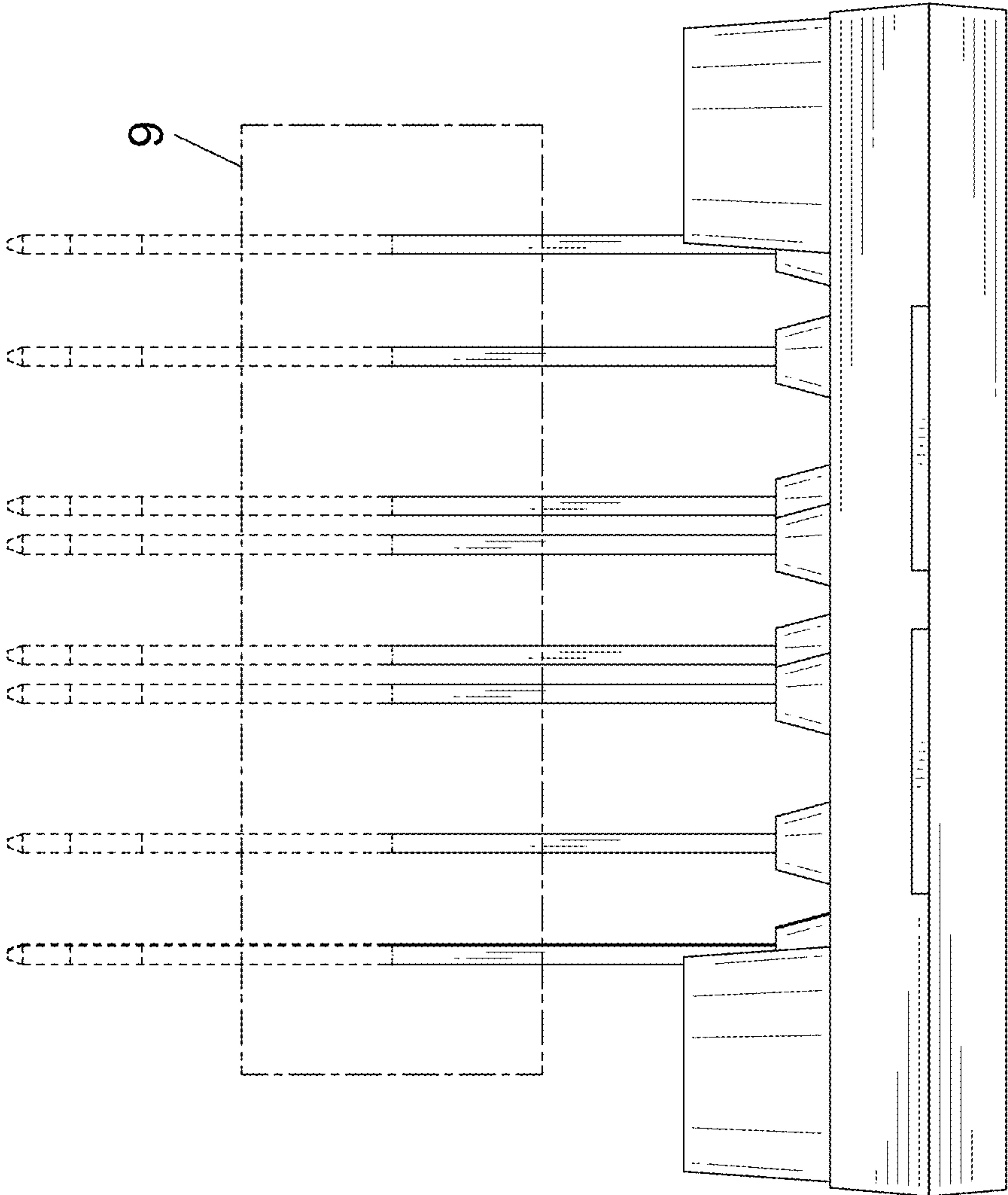


FIG. 8

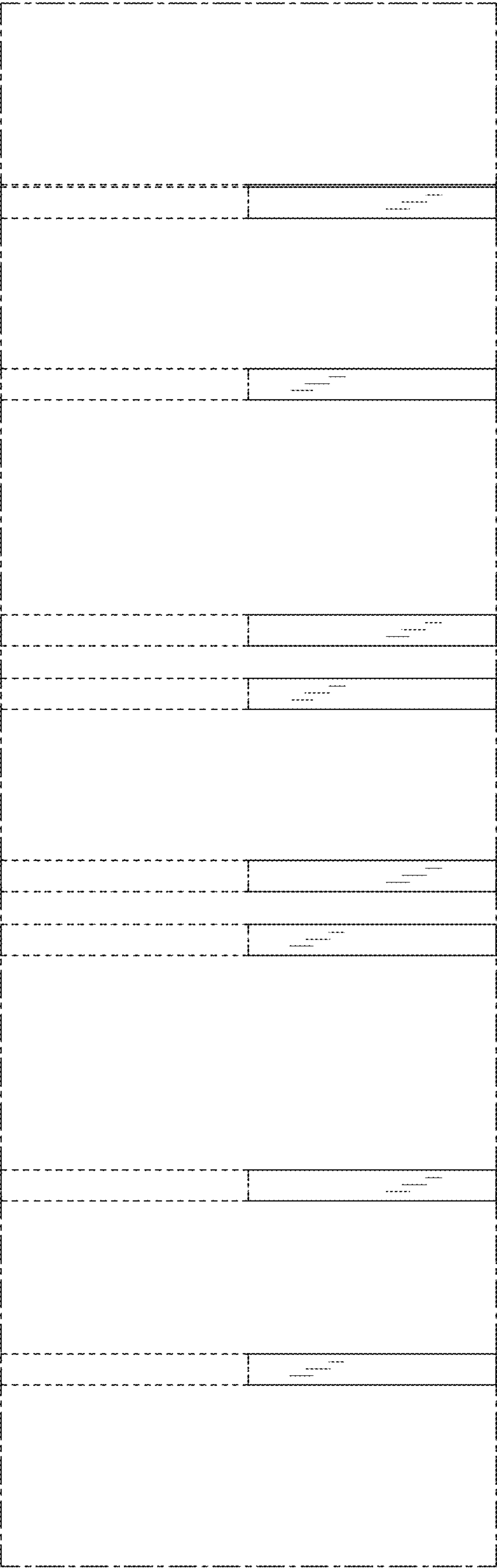


FIG.9

